

Material Composition Data

Product: GXO-3204

Page 1



GXO-3204 - 2520 SM Oscillator					Sub-Assembly
Sub-Assembly	Material	Substance	CAS No	Mass (mg)	% by mass
Ag85Cu15 Solder	Copper	Cu	7440-50-8	0.029	15.10
	Silver	Ag	7440-22-4	0.163	84.90
Ceramic 2520 SMD Lid	Carbon	C	7440-44-0	0.000	0.00
	Cobalt	Co	7440-48-4	0.630	17.17
	Iron	Fe	7439-89-6	1.954	53.26
	Manganese	Mn	7439-96-5	0.009	0.25
	Nickel	Ni	7440-02-0	1.072	29.22
	Silicon	Si	7440-21-3	0.004	0.11
Clk Osc IC	Si	SiO2	14808-60-7	0.193	13.54
	SiO2	SiO2	14808-60-7	1.232	86.46
Quartz blank	SiO2	SiO2	14808-60-7	0.340	100.00
SMD Base Ceramic	Aluminium oxide	Al2O3	1344-28-1	3.786	92.45
	Calcium-oxide	CaO	1305-78-8	0.021	0.51
	Chromium(III)oxide	Cr2O3	1308-38-9	0.021	0.51
	Magnesium-oxide	MgO	1309-48-4	0.021	0.51
	Molybdenum	Mo	7439-98-7	0.041	1.00
	Silicon dioxide	SiO2	14808-60-7	0.205	5.01
SMD Base Electrode	Cobalt	Co	7440-48-4	0.247	100.00
SMD Base Gold Plating	Gold	Au	7440-57-5	0.030	78.95
	Thallium	Tl	7440-28-0	0.008	21.05
SMD Base Seal Ring	Carbon	C	7440-44-0	0.000	0.00
	Iron	Fe	7439-89-6	0.550	64.25
	Manganese	Mn	7439-96-5	0.003	0.35
	Nickel	Ni	7440-02-0	0.302	35.28
	Silicon	Si	7440-21-3	0.001	0.12
Silver Epoxy	Epoxy resin	Epoxy resin trade secret	0	0.060	30.00
	Silver	Ag	7440-22-4	0.140	70.00
Silver Plating	Silver	Ag	7440-22-4	0.001	100.00
Total Mass:				11.063 mg	

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